PRODUCT CHANGE NOTICE		
PART NUMBER(S):	PCN No.: 06-0130-02a	
Please see attachment.	DATE: June 23, 2006	
PART DESCRIPTION:		
Power Management and Interface Products – Change in Wafer Fabrication Site		
LEVEL OF CHANGE:		
[X] Level I, Customer Approval.	[] Level II, Customer Information.	
PRODUCT ATTRIBUTE AFFECTED:		
[] Material Change [] Design Change [X] Process Change	Data Sheet ChangePackage ChangePacking / Shipping	
[X] Other, Explain: Wafer Fabrication Site Transfer		
DESCRIPTION OF CHANGE:		
Announcing transfer of certain Power Management and Interface Products from Hillview wafer fabrication facility to wafer foundry EPISIL. See attached Product List no. 02a.		
REASON FOR CHANGE:		
Power Management and Interface products as listed are being transferred to external wafer foundry, due to cessation of operations of the Sipex Hillview Wafer Fabrication manufacturing site.		

FABRICATION PROCESS QUALIFICATION

COMPLETED (DATE): October 15, 2006

PRODUCT CHARACTERIZATION COMPLETED: October 22,

SAMPLES* AVAILABLE (DATE): December 30, 2006

2006

^{*} Samples representative of product from the Product Family being transferred.



PRODUCT CHANGE NOTICE	
EARLIEST DATE OF PRODUCTION SHIPMENTS: December 30, 2006	
EFFECTIVITY CHANGE DATE OR DATE CODE: Work week associated with earliest production shipment.	
[] STANDARD DISTRIBUTION	[X] CUSTOM DISTRIBUTION
PERSON TO CONTACT WITH QUESTION	S:
Fred Claussen	
VP Quality Assurance and Reliability Sipex Corporation Phone Number: 408-935-7644 FAX NUMBER: 408-935-7678	



PRODUCT CHANGE NOTICE

PCN No.: 06-0130-02a

List 2

SP508CF

SP508CF-L

SP508EF

SP508EF-L

SP509CF

SP509CF-L

SP508CF

SP508CF-L

SP508EF

SP508EF-L

SP509CF

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